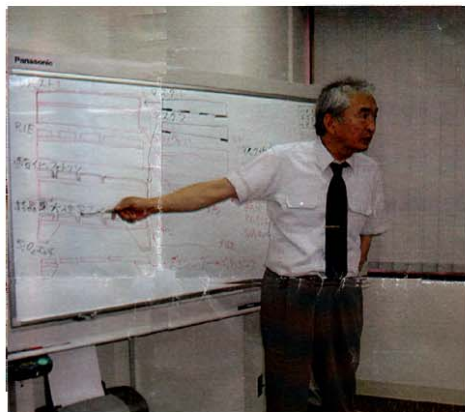


H6 Fabrication of MEMS strap for cellular phone by processing wafers in 9 MEMS factories in Japan (10th anniversary of SEMI microsystem / MEMS seminar) Collaboration between companies (2006/12/6)

Design M. Esashi



0) SOI wafer **OLYMPUS**



1) Oxidation & front oxide etching



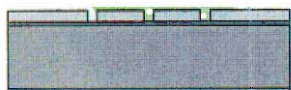
RICOH

2) Photolithography **RICOH**



MEMS CORE

3) Si RIE **RICOH**

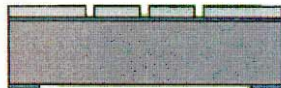


4) Photolithography **RICOH**

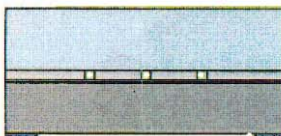


MEMS CORE

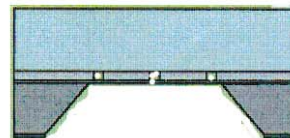
5) Oxide dry etching **RICOH**



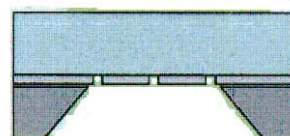
6) Anodic bonding **OMRON**



7) Si anisotropic etching **OMRON**



8) Oxide etching **OMRON**



9) Dicing **Fuji Electric**

